

1. A wet processing apparatus comprising:
 - a tank to contain a fluid;
 - a drain opening in said tank; and
 - a regulating means disposed in said tank and over said
- 5 drain opening to control the draining rate and the draining direction of said fluid.
2. The apparatus according to Claim 1 wherein said drain opening is located on the bottom surface of said tank.
3. The apparatus according to Claim 1 wherein said fluid comprises de-ionized water.
4. The apparatus according to Claim 1 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region.
5. The apparatus according to Claim 1 wherein said regulating means comprises a regulating plate dividing said tank into a processing region and a draining region, and wherein, during draining, fluid in said tank flows from
- 5 said processing region through said regulating plate, through said draining region, and out said drain opening.

6. The apparatus according to Claim 5 wherein said regulating plate comprises polyetheretherkefone (PEEK).
7. The apparatus according to Claim 5 wherein said regulating plate comprises a plurality of slats and openings.
8. The apparatus according to Claim 7 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region wherein said integrated circuit wafers are oriented in the same
5 direction as said slats and openings.
9. The apparatus according to Claim 7 wherein said slats are oriented at an angle of between about 0° and about 45° with respect to the plane of said regulating plate.
10. The apparatus according to Claim 7 wherein one said slat substantially covers said drain opening.
11. The apparatus according to Claim 10 wherein additional said slats are angled with respect to the plane of said regulating plate.

12. A wet processing apparatus comprising:
- a tank;
 - a drain opening in said tank; and
 - a regulating plate dividing said tank into a
- 5 processing region and a draining region, wherein said regulating plate comprises a plurality of slats and openings, wherein, during draining, fluid in said tank flows from said processing region through said regulating plate, through said draining region, and out said drain
- 10 opening.
13. The apparatus according to Claim 12 wherein said fluid comprises de-ionized water.
14. The apparatus according to Claim 12 wherein additional said slats are angled with respect to the plane of said regulating plate.
15. The apparatus according to Claim 12 wherein said regulating plate comprises polyetheretherkefone (PEEK).

16. The apparatus according to Claim 12 wherein said slats are oriented at an angle of between about 0° and about 45° with respect to the plane of said regulating plate.

17. The apparatus according to Claim 12 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region wherein said integrated circuit wafers are oriented in the same
5 direction as said slats and openings.

18. The apparatus according to Claim 12 wherein one said slat substantially covers said drain opening.

19. The apparatus according to Claim 18 wherein additional said slats are angled with respect to the plane of said regulating plate.

20. An integrated circuit wet processing method comprising:

providing a tank having a drain opening;

providing a regulating means disposed in said tank and
5 over said drain opening to control the draining rate and the draining direction of said fluid;

immersing a plurality of integrated circuit wafers
into said processing region;

filling said tank with a fluid; and

10 thereafter draining said fluid from said tank wherein
said fluid flows through said regulating means.

21. The method according to Claim 20 wherein said drain
opening is located on the bottom surface of said tank.

22. The method according to Claim 20 wherein said fluid
comprises de-ionized water.

23. The method according to Claim 20 wherein said
regulating means comprises a regulating plate dividing said
tank into a processing region and a draining region, and
wherein, during draining, fluid in said tank flows from
5 said processing region through said regulating plate,
through said draining region, and out said drain opening.

24. The method according to Claim 23 wherein said
regulating plate comprises a plurality of slats and
openings.

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25. The method according to Claim 24 wherein said integrated circuit wafers are oriented in the same direction as said slats and openings.

26. The method according to Claim 24 wherein said slats are oriented at an angle of between about 0° and about 45° with respect to the plane of said regulating plate.

27. The method according to Claim 24 wherein one said slat substantially covers said drain opening.

28. The method according to Claim 27 wherein additional said slats are angled with respect to the plane of said regulating plate.